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Details

Product Status	Active
Number of LABs/CLBs	645
Number of Logic Elements/Cells	10320
Total RAM Bits	423936
Number of I/O	91
Number of Gates	
Voltage - Supply	0.97V ~ 1.03V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	144-LQFP Exposed Pad
Supplier Device Package	144-EQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce10e22i8In

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Figure 3–7 shows a timing waveform for read and write operations in single-port mode with unregistered outputs. Registering the outputs of the RAM simply delays the q output by one clock cycle.



Figure 3–7. Cyclone IV Devices Single-Port Mode Timing Waveform

Simple Dual-Port Mode

Simple dual-port mode supports simultaneous read and write operations to different locations. Figure 3–8 shows the simple dual-port memory configuration.

Figure 3–8. Cyclone IV Devices Simple Dual-Port Memory (1)



Note to Figure 3-8:

(1) Simple dual-port RAM supports input or output clock mode in addition to the read or write clock mode shown.

Cyclone IV devices M9K memory blocks support mixed-width configurations, allowing different read and write port widths. Table 3–3 lists mixed-width configurations.

 Table 3–3.
 Cyclone IV Devices M9K Block Mixed-Width Configurations (Simple Dual-Port Mode)
 (Part 1 of 2)

Bood Bort					Write Port				
neau ruit	8192 × 1	4096 × 2	2048 × 4	1024 × 8	512 × 16	256 × 32	1024 × 9	512 × 18	256 × 36
8192 × 1	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	—	—	_
4096 × 2	\checkmark	\checkmark	~	\checkmark	\checkmark	\checkmark	—	—	—
2048 × 4	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	—	—	—
1024 × 8	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	—	—	—

GCLK Network Clock	GCLK Networks																			
Sources	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19
CLK15/DIFFCLK_6p (2)	—	—	_	—	—		—	—		—	—	_	_		_	~	_	_	~	—
PLL_1_C0 (3)	\checkmark	—		\checkmark	—	—	—	—	—	—	—	_	—	—	_	—	_	_	—	—
PLL_1_C1 (3)	—	\checkmark	_	—	\checkmark	—	—	—	—		—		—				_	_	_	—
PLL_1_C2 (3)	\checkmark	—	\checkmark	—	—	—	—	—	—	—	—		—	_		_			—	—
PLL_1_C3 (3)	—	~		~			_		_											—
PLL_1_C4 (3)	—	_	\checkmark	_	~	_	_	_	_		_								—	—
PLL_2_C0 (3)	—	—		—		~	—	—	~		—									—
PLL_2_C1 (3)	—	—	—	—	—	—	\checkmark	—	—	\checkmark	—		—	_			—	—	—	—
PLL_2_C2 (3)	—	_		_		\checkmark		~			_									—
PLL_2_C3 (3)	_	—	—	—	—	—	\checkmark	—	\checkmark	—	—	—	—	—	—	—	—	—	—	—
PLL_2_C4 (3)	—	—	—	—	—	—	—	\checkmark	—	\checkmark	—	—	—	—	—	—	—	—	—	—
PLL_3_C0	—	—	—	—	—	—	—	—	—	—	\checkmark	—	—	\checkmark	—	—	—	—	—	—
PLL_3_C1	—	—	—	—	—	—	—	—	—	—	—	\checkmark	—	_	\checkmark	—	—	—	—	—
PLL_3_C2	—	—	—	—	—	—	—	—	—	—	\checkmark	—	\checkmark	—	—	—	—	—	—	—
PLL_3_C3	—	—	—	—	—	—	—	—	—	—	—	\checkmark	—	\checkmark	—	—	—	—	—	—
PLL_3_C4	—	—	—	—	—	—	—	—	—	—	—	—	\checkmark	_	\checkmark	—	—	—	—	—
PLL_4_C0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	\checkmark	—	—	\checkmark	—
PLL_4_C1	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	\checkmark	—	—	\checkmark
PLL_4_C2	—	—		—	—	—	—	—	—		—		—	_		\checkmark	—	\checkmark	—	—
PLL_4_C3	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	\checkmark	—	\checkmark	—
PLL_4_C4	—	—	—	—	—	—	—	—	—	—	—	—	—	_	—	—	—	\checkmark	—	\checkmark
DPCLK0	\checkmark	—	—	—	—	—	—	—	—		—		—	—		—	—	—	—	—
DPCLK1	—	\checkmark	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
DPCLK7 (4)																				
CDPCLK0, Or	-	—	\checkmark	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
CDPCLK7 (2), (5)																				

 Table 5–3.
 GCLK Network Connections for Cyclone IV E Devices (1)
 (Part 2 of 3)

Figure 5–1 shows the clock control block.

Figure 5–1. Clock Control Block



Notes to Figure 5-1:

- (1) The clkswitch signal can either be set through the configuration file or dynamically set when using the manual PLL switchover feature. The output of the multiplexer is the input clock (f_{IN}) for the PLL.
- (2) The clkselect[1..0] signals are fed by internal logic and are used to dynamically select the clock source for the GCLK when the device is in user mode.
- (3) The static clock select signals are set in the configuration file. Therefore, dynamic control when the device is in user mode is not feasible.
- (4) Two out of four PLL clock outputs are selected from adjacent PLLs to drive into the clock control block.
- (5) You can use internal logic to enable or disable the GCLK in user mode.
- (6) CLK [12] is not available on the left side of Cyclone IV E devices.

Each PLL generates five clock outputs through the c[4..0] counters. Two of these clocks can drive the GCLK through a clock control block, as shown in Figure 5–1.

For more information about how to use the clock control block in the Quartus II software, refer to the *ALTCLKCTRL Megafunction User Guide*.



Figure 5–23 shows a functional simulation of the PLL reconfiguration feature.

Figure 5-23. PLL Reconfiguration Scan Chain

When reconfiguring the counter clock frequency, the corresponding counter phase shift settings cannot be reconfigured using the same interface. You can reconfigure phase shifts in real time using the dynamic phase shift reconfiguration interface. If you reconfigure the counter frequency, but wish to keep the same non-zero phase shift setting (for example, 90°) on the clock output, you must reconfigure the phase shift after reconfiguring the counter clock frequency.

Post-Scale Counters (C0 to C4)

You can configure multiply or divide values and duty cycle of post-scale counters in real time. Each counter has an 8-bit high time setting and an 8-bit low time setting. The duty cycle is the ratio of output high or low time to the total cycle time, that is the sum of the two. Additionally, these counters have two control bits, rbypass, for bypassing the counter, and rselodd, to select the output clock duty cycle.

When the rbypass bit is set to 1, it bypasses the counter, resulting in a divide by one. When this bit is set to 0, the PLL computes the effective division of the VCO output frequency based on the high and low time counters. For example, if the post-scale divide factor is 10, the high and low count values are set to 5 and 5, to achieve a 50–50% duty cycle. The PLL implements this duty cycle by transitioning the output clock from high-to-low on the rising edge of the VCO output clock. However, a 4 and 6 setting for the high and low count values, respectively, would produce an output clock with a 40–60% duty cycle.

The rselodd bit indicates an odd divide factor for the VCO output frequency with a 50% duty cycle. For example, if the post-scale divide factor is three, the high and low time count values are 2 and 1, respectively, to achieve this division. This implies a 67%–33% duty cycle. If you need a 50%–50% duty cycle, you must set the rselodd control bit to 1 to achieve this duty cycle despite an odd division factor. The PLL implements this duty cycle by transitioning the output clock from high-to-low on a falling edge of the VCO output clock. When you set rselodd = 1, subtract 0.5 cycles from the high time and add 0.5 cycles to the low time.

For example:

■ High time count = 2 cycles

The IOE registers in each I/O block share the same source for the preset or clear features. You can program preset or clear for each individual IOE, but you cannot use both features simultaneously. You can also program the registers to power-up high or low after configuration is complete. If programmed to power-up low, an asynchronous clear can control the registers. If programmed to power-up high, an asynchronous preset can control the registers. This feature prevents the inadvertent activation of the active-low input of another device upon power-up. If one register in an IOE uses a preset or clear signal, all registers in the IOE must use that same signal if they require preset or clear. Additionally, a synchronous reset signal is available for the IOE registers.

***** For more information about the input and output pin delay settings, refer to the *Area and Timing Optimization* chapter in volume 2 of the *Quartus II Handbook*.

PCI-Clamp Diode

Cyclone IV devices provide an optional PCI-clamp diode enabled input and output for each I/O pin. Dual-purpose configuration pins support the diode in user mode if the specific pins are not used as configuration pins for the selected configuration scheme. For example, if you are using the active serial (AS) configuration scheme, you cannot use the clamp diode on the ASDO and nCSO pins in user mode. Dedicated configuration pins do not support the on-chip diode.

The PCI-clamp diode is available for the following I/O standards:

- 3.3-V LVTTL
- 3.3-V LVCMOS
- 3.0-V LVTTL
- 3.0-V LVCMOS
- 2.5-V LVTTL/LVCMOS
- PCI
- PCI-X

If the input I/O standard is one of the listed standards, the PCI-clamp diode is enabled by default in the Quartus II software.

OCT Support

Cyclone IV devices feature OCT to provide I/O impedance matching and termination capabilities. OCT helps prevent reflections and maintain signal integrity while minimizing the need for external resistors in high pin-count ball grid array (BGA) packages. Cyclone IV devices provide I/O driver on-chip impedance matching and R_S OCT for single-ended outputs and bidirectional pins.

When using R_S OCT, programmable current strength is not available.

There are two ways to implement OCT in Cyclone IV devices:

- OCT with calibration
- OCT without calibration

LVPECL I/O Support in Cyclone IV Devices

The LVPECL I/O standard is a differential interface standard that requires a 2.5-V V_{CCIO} . This standard is used in applications involving video graphics, telecommunications, data communications, and clock distribution. Cyclone IV devices support the LVPECL input standard at the dedicated clock input pins only. The LVPECL receiver requires an external 100- Ω termination resistor between the two signals at the input buffer.

 For the LVPECL I/O standard electrical specification, refer to the Cyclone IV Device Datasheet chapter.

AC coupling is required when the LVPECL common mode voltage of the output buffer is higher than the Cyclone IV devices LVPECL input common mode voltage.

Figure 6–18 shows the AC-coupled termination scheme. The $50-\Omega$ resistors used at the receiver are external to the device. DC-coupled LVPECL is supported if the LVPECL output common mode voltage is in the Cyclone IV devices LVPECL input buffer specification (refer to Figure 6–19).

Figure 6–18. LVPECL AC-Coupled Termination (1)



Note to Figure 6–18:

(1) The LVPECL AC-coupled termination is applicable only when an Altera FPGA transmitter is used.

Figure 6–19 shows the LVPECL DC-coupled termination.

Figure 6–19. LVPECL DC-Coupled Termination (1)



Note to Figure 6–19:

(1) The LVPECL DC-coupled termination is applicable only when an Altera FPGA transmitter is used.

Device	Package	Side	Number ×8 Groups	Number ×9 Groups	Number ×16 Groups	Number ×18 Groups	Number ×32 Groups	Number ×36 Groups
		Left	4	4	2	2	1	1
484-p EP4CE40 EP4CE55 484-p EP4CE75	494 pin LIPCA	Right	4	4	2	2	1	1
	404-piii 0BGA	Bottom	4	4	2	2	1	1
		Тор	4	4	2	2	1	1
	484-pin FBGA	Left	4	4	2	2	1	1
		Right	4	4	2	2	1	1
		Bottom	4	4	2	2	1	1
		Тор	4	4	2	2	1	1
	700	Left	4	4	2	2	1	1
		Right	4	4	2	2	1	1
	700-ріп ғваа	Bottom	6	6	2	2	1	1
		Тор	6	6	2	2	1	1

|--|

Notes to Table 7-2:

(1) Some of the DQ pins can be used as RUP and RDN pins. You cannot use these groups if you are using these pins as RUP and RDN pins for OCT calibration.

(2) Some of the DQ pins can be used as RUP pins while the DM pins can be used as RDN pins. You cannot use these groups if you are using the RUP and RDN pins for OCT calibration.

(3) There is no DM pin support for these groups.

(4) PLLCLKOUT3n and PLLCLKOUT3p pins are shared with the DQ or DM pins to gain ×8 DQ group. You cannot use these groups if you are using PLLCLKOUT3n and PLLCLKOUT3p.

To For more information about device package outline, refer to the Device Packaging Specifications webpage.

DQS pins are listed in the Cyclone IV pin tables as DQSXY, in which X indicates the DQS grouping number and Y indicates whether the group is located on the top (T), bottom (B), or right (R) side of the device. Similarly, the corresponding DQ pins are marked as DQXY, in which the X denotes the DQ grouping number and Y denotes whether the group is located on the top (T), bottom (B), or right (R) side of the device. For example, DQS2T indicates a DQS pin belonging to group 2, located on the top side of the device. Similarly, the DQ pins belonging to that group is shown as DQ2T.

Each DQ group is associated with its corresponding DQS pins, as defined in the Cyclone IV pin tables. For example:

- For DDR2 or DDR SDRAM, ×8 DQ group DQ3B[7..0] pins are associated with the DQS3B pin (same 3B group index)
- For QDR II SRAM, ×9 Q read-data group DQ3T[8..0] pins are associated with DQS0T/CQ0T and DQS1T/CQ0T# pins (same 0T group index)

The Quartus[®] II software issues an error message if a DQ group is not placed properly with its associated DQS.

the device, must be stored in the external host device. Figure 8–19 shows the configuration interface connections between the Cyclone IV devices and an external device for single-device configuration.





Notes to Figure 8-19:

- (1) Connect the pull-up resistor to a supply that provides an acceptable input signal for the device. V_{CC} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host.
- (2) The nCEO pin is left unconnected or used as a user I/O pin when it does not feed the nCE pin of another device.
- (3) The MSEL pin settings vary for different configuration voltage standards and POR time. To connect the MSEL pins, refer to Table 8–4 on page 8–8 and Table 8–5 on page 8–9. Connect the MSEL pins directly to V_{CCA} or GND.
- (4) All I/O inputs must maintain a maximum AC voltage of 4.1 V. DATA [7..0] and DCLK must fit the maximum overshoot outlined in Equation 8–1 on page 8–5.

After nSTATUS is released, the device is ready to receive configuration data and the configuration stage begins. When nSTATUS is pulled high, the external host device places the configuration data one byte at a time on the DATA[7..0]pins.

Cyclone IV devices receive configuration data on the DATA[7..0] pins and the clock is received on the DCLK pin. Data is latched into the device on the rising edge of DCLK. Data is continuously clocked into the target device until CONF_DONE goes high. The CONF_DONE pin goes high one byte early in FPP configuration mode. The last byte is required for serial configuration (AS and PS) modes.

Two DCLK falling edges are required after CONF_DONE goes high to begin initialization of the device.

Supplying a clock on CLKUSR does not affect the configuration process. After the CONF_DONE pin goes high, CLKUSR is enabled after the time specified as t_{CD2CU} . After this time period elapses, Cyclone IV devices require 3,192 clock cycles to initialize properly and enter user mode. For more information about the supported CLKUSR f_{MAX} value for Cyclone IV devices, refer to Table 8–13 on page 8–44.

The INIT_DONE pin is released and pulled high when initialization is complete. The external host device must be able to detect this low-to-high transition, which signals the device has entered user mode. When initialization is complete, the device enters user mode. In user mode, the user I/O pins no longer have weak pull-up resistors and function as assigned in your design.

JTAG instructions have precedence over any other configuration modes. Therefore, JTAG configuration can take place without waiting for other configuration modes to complete. For example, if you attempt JTAG configuration in Cyclone IV devices during PS configuration, PS configuration terminates and JTAG configuration begins. If the MSEL pins are set to AS mode, the Cyclone IV device does not output a DCLK signal when JTAG configuration takes place.

The four required pins for a device operating in JTAG mode are TDI, TDO, TMS, and TCK. All the JTAG input pins are powered by the V_{CCIO} pin and support the LVTTL I/O standard only. All user I/O pins are tri-stated during JTAG configuration. Table 8-14 explains the function of each JTAG pin.

Pin Name Pin Type Description Serial input pin for instructions as well as test and programming data. Data shifts in on the Test data rising edge of TCK. If the JTAG interface is not required on the board, the JTAG circuitry is TDI disabled by connecting this pin to V_{CC} . TDI pin has weak internal pull-up resistors (typically 25 input kΩ). Serial data output pin for instructions as well as test and programming data. Data shifts out on Test data the falling edge of TCK. The pin is tri-stated if data is not being shifted out of the device. If the TDO output JTAG interface is not required on the board, the JTAG circuitry is disabled by leaving this pin unconnected. Input pin that provides the control signal to determine the transitions of the TAP controller state machine. Transitions in the state machine occur on the rising edge of TCK. Therefore, Test mode TMS must be set up before the rising edge of TCK. TMS is evaluated on the rising edge of TCK. TMS select If the JTAG interface is not required on the board, the JTAG circuitry is disabled by connecting this pin to V_{CC} . TMS pin has weak internal pull-up resistors (typically 25 k Ω). The clock input to the BST circuitry. Some operations occur at the rising edge, while others Test clock occur at the falling edge. If the JTAG interface is not required on the board, the JTAG circuitry TCK input

Table 8–14. Dedicated JTAG Pins

You can download data to the device through the USB-Blaster, MasterBlaster, ByteBlaster II, or ByteBlasterMV download cable, or the EthernetBlaster communications cable during JTAG configuration. Configuring devices with a cable is similar to programming devices in-system. Figure 8-23 and Figure 8-24 show the JTAG configuration of a single Cyclone IV device.

is disabled by connecting this pin to GND. The TCK pin has an internal weak pull-down resistor.

Transmitter Output Buffer

Figure 1–11 shows the transmitter output buffer block diagram.





Note to Figure 1-11:

(1) Receiver detect function is specific for PCIe protocol implementation only. For more information, refer to "PCI Express (PIPE) Mode" on page 1–52.

The Cyclone IV GX transmitter output buffers support the **1.5-V PCML** I/O standard and are powered by VCCH_GXB power pins with 2.5-V supply. The 2.5-V supply on VCCH_GXB pins are regulated internally to 1.5-V for the transmitter output buffers. The transmitter output buffers support the following additional features:

- Programmable differential output voltage (V_{OD})—customizes the V_{OD} up to 1200 mV to handle different trace lengths, various backplanes, and various receiver requirements.
- Programmable pre-emphasis—boosts high-frequency components in the transmitted signal to maximize the data eye opening at the far-end. The high-frequency components might be attenuated in the transmission media due to data-dependent jitter and intersymbol interference (ISI) effects. The requirement for pre-emphasis increases as the data rates through legacy backplanes increase.
- Programmable differential on-chip termination (OCT)—provides calibrated OCT at differential 100 Ω or 150 Ω with on-chip transmitter common mode voltage (V_{CM}) at 0.65 V. V_{CM} is tri-stated when you disable the OCT to use external termination.
- Disable OCT to use external termination if the link requires a 85 Ω termination, such as when you are interfacing with certain PCIe Gen1 or Gen2 capable devices.
- The Cyclone IV GX transmitter output buffers are current-mode drivers. The resulting V_{OD} voltage is therefore a function of the transmitter termination value. For lists of supported V_{OD} settings, refer to the *Cyclone IV Device Data Sheet*.

In a DC-coupled link, the transmitter DC common mode voltage is seen unblocked at the receiver input buffer as shown in Figure 1–13. The link common mode voltage depends on the transmitter common mode voltage and the receiver common mode voltage. When using the receiver OCT and on-chip biasing circuitry in a DC coupled link, you must ensure the transmitter common mode voltage is compatible with the receiver common mode requirements. If you disable the OCT, you must terminate and bias the receiver externally and ensure compatibility between the transmitter and the receiver common mode voltage.





Figure 1–14 shows the receiver input buffer block diagram.





The receiver input buffers support the following features:

Byte Deserializer

The byte deserializer halves the FPGA fabric-transceiver interface frequency while doubles the parallel data width to the FPGA fabric.

For example, when operating an EP4CGX150 receiver channel at 3.125 Gbps with deserialization factor of 10, the receiver PCS datapath runs at 312.5 MHz. The byte deserializer converts the 10-bit data at 312.5 MHz into 20-bit data at 156.25 MHz before forwarding the data to the FPGA fabric.

Byte Ordering

In the 16- or 20-bit FPGA fabric-transceiver interface, the byte deserializer receives one data byte (8 or 10 bits) and deserializes it into two data bytes (16 or 20 bits). Depending on when the receiver PCS logic comes out of reset, the byte ordering at the output of the byte deserializer may not match the original byte ordering of the transmitted data. The byte misalignment resulting from byte deserialization is unpredictable because it depends on which byte is being received by the byte deserializer when it comes out of reset.

Figure 1–23 shows a scenario where the most significant byte and the least significant byte of the two-byte transmitter data appears straddled across two word boundaries after the data is deserialized at the receiver.

Figure 1–23. Example of Byte Deserializer at the Receiver



The byte ordering block restores the proper byte ordering by performing the following actions:

- Look for the user-programmed byte ordering pattern in the byte-deserialized data
- Inserts a user-programmed pad byte if the user-programmed byte ordering pattern is found in the most significant byte position

You must select a byte ordering pattern that you know appears at the least significant byte position of the parallel transmitter data.

The byte ordering block is supported in the following receiver configurations:

- 16-bit FPGA fabric-transceiver interface, 8B/10B disabled, and the word aligner in manual alignment mode. Program a custom 8-bit byte ordering pattern and 8-bit pad byte.
- I6-bit FPGA fabric-transceiver interface, 8B/10B enabled, and the word aligner in automatic synchronization state machine mode. Program a custom 9-bit byte ordering pattern and 9-bit pad byte. The MSB of the 9-bit byte ordering pattern and pad byte represents the control identifier of the 8B/10B decoded data.

Figure 1–57 shows an example of even numbers of /Dx.y/ between the last automatically sent /K28.5/ and the first user-sent /K28.5/. The first user-sent /K28.5/ code group received at an odd code group boundary in cycle n + 3 takes the receiver synchronization state machine in Loss-of-Sync state. The first synchronization ordered-set /K28.5/Dx.y/ in cycles n + 3 and n + 4 is discounted and three additional ordered sets are required for successful synchronization.





Running Disparity Preservation with Idle Ordered Set

During idle ordered sets transmission in GIGE mode, the transmitter ensures a negative running disparity at the end of an idle ordered set. Any /Dx.y/, except for /D21.5/ (part of /C1/ ordered set) or /D2.2/ (part of /C2/ ordered set) following a /K28.5/ is automatically replaced with either of the following:

- A /D5.6/ (/I1/ ordered set) if the running disparity before /K28.5/ is positive
- A /D16.2/ (/I2/ ordered set) if the running disparity before /K28.5/ is negative

Lane Synchronization

In GIGE mode, the word aligner is configured in automatic synchronization state machine mode that complies with the IEEE P802.3ae standard. A synchronization ordered set is a /K28.5/ code group followed by an odd number of valid /Dx.y/ code groups. Table 1–19 lists the synchronization state machine parameters that implements the GbE-compliant synchronization.

Parameter	Value
Number of valid synchronization ordered sets received to achieve synchronization	3
Number of erroneous code groups received to lose synchronization	4
Number of continuous good code groups received to reduce the error count by one	4

Note to Table 1-19:

(1) The word aligner supports 7-bit and 10-bit pattern lengths in GIGE mode.

Document Revision History

Table 1–30 lists the revision history for this chapter.

Table 1-30.	Document	Revision	History
	Boounione	1101101011	

Date	Version	Changes					
		■ Updated the GiGE row in Table 1–14.					
February 2015	3.7	 Updated the "GIGE Mode" section. 					
		 Updated the note in the "Clock Frequency Compensation" section. 					
October 2013	3.6	Updated Figure 1–15 and Table 1–4.					
May 2013	3.5	Updated Table 1–27 by setting "rx_locktodata" and "rx_locktorefclk" to "Input"					
		■ Updated the data rate for the V-by-one protocol and the F324 package support in HD-SDI in Table 1–1.					
October 2012	3.4	■ Updated note (1) to Figure 1–27.					
		 Added latency information to Figure 1–67. 					
November 2011	2.2	 Updated "Word Aligner" and "Basic Mode" sections. 					
	3.3	■ Updated Figure 1–37.					
December 2010	3.2	 Updated for the Quartus II software version 10.1 release. 					
		■ Updated Table 1–1, Table 1–5, Table 1–11, Table 1–14, Table 1–24, Table 1–25, Table 1–26, Table 1–27, Table 1–28, and Table 1–29.					
		 Updated "8B/10B Encoder", "Transmitter Output Buffer", "Receiver Input Buffer", "Clock Data Recovery", "Miscellaneous Transmitter PCS Features", "Miscellaneous Receiver PCS Feature", "Input Reference Clocking", "PCI Express (PIPE) Mode", "Channel Deskewing", "Lane Synchronization", "Serial Loopback", and "Self Test Modes" sections. 					
		■ Added Figure 1–9, Figure 1–10, Figure 1–19, Figure 1–20, and Figure 1–43.					
		■ Updated Figure 1–53, Figure 1–55, Figure 1–59, Figure 1–60, Figure 1–69, Figure 1–70, Figure 1–71, Figure 1–72, Figure 1–73, and Figure 1–74.					
November 2010	3.1	Updated Introductory information.					
		 Updated information for the Quartus II software version 10.0 release. 					
July 2010	3.0	 Reset control, power down, and dynamic reconfiguration information moved to new Cyclone IV Reset Control and Power Down and Cyclone IV Dynamic Reconfiguration chapters. 					

Clocking/Interface Options

The following describes the **Clocking/Interface** options available in Cyclone IV GX devices. The core clocking setup describes the transceiver core clocks that are the write and read clocks of the Transmit Phase Compensation FIFO and the Receive Phase Compensation FIFO, respectively. Core clocking is classified as transmitter core clocking and receiver core clocking.

Table 3–6 lists the supported clocking interface settings for channel reconfiguration mode in Cyclone IV GX devices.

ALTGX Setting	Description							
Dynamic Reconfiguration Channel Internal and Interface Settings								
	Select one of the available options:							
How should the receivers be	Share a single transmitter core clock between receivers							
clocked?	Use the respective channel transmitter core clocks							
	 Use the respective channel receiver core clocks 							
	Select one of the available options:							
How should the transmitters be	Share a single transmitter core clock between transmitters							
	 Use the respective channel transmitter core clocks 							

 Table 3–6. Dynamic Reconfiguration Clocking Interface Settings in Channel Reconfiguration

 Mode

Transmitter core clocking refers to the clock that is used to write the parallel data from the FPGA fabric into the Transmit Phase Compensation FIFO. You can use one of the following clocks to write into the Transmit Phase Compensation FIFO:

- tx_coreclk—you can use a clock of the same frequency as tx_clkout from the FPGA fabric to provide the write clock to the Transmit Phase Compensation FIFO. If you use tx_coreclk, it overrides the tx_clkout options in the ALTGX MegaWizard Plug-In Manager.
- tx_clkout—the Quartus II software automatically routes tx_clkout to the FPGA fabric and back into the Transmit Phase Compensation FIFO.

Option 1: Share a Single Transmitter Core Clock Between Transmitters

- Enable this option if you want tx_clkout of the first channel (channel 0) of the transceiver block to provide the write clock to the Transmitter Phase Compensation FIFOs of the remaining channels in the transceiver block.
- This option is typically enabled when all the channels of a transceiver block have the same functional mode and data rate and are reconfigured to the identical functional mode and data rate.

Figure 3–11 shows the sharing of channel 0's tx_clkout between all four regular channels of a transceiver block.





Embedded Multiplier Specifications

Table 1–26 lists the embedded multiplier specifications for Cyclone IV devices.

Table 1–26. Embedded Multiplier Specifications for Cyclone IV Devices

Mada	Resources Used		Performance										
wode	Number of Multipliers	C6	C7, I7, A7	C8	C8L, 18L	C9L	Unit						
9 × 9-bit multiplier	1	340	300	260	240	175	MHz						
18 × 18-bit multiplier	1	287	250	200	185	135	MHz						

Memory Block Specifications

Table 1–27 lists the M9K memory block specifications for Cyclone IV devices.

Table 1-27.	Memory Block	Performance S	pecifications t	for C	yclone IV Devices
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		Resou	rces Used						
Memory	Mode		M9K Memory	C6	C7, I7, A7	C8	C8L, 18L	C9L	Unit
M9K Block	FIFO 256 × 36	47	1	315	274	238	200	157	MHz
	Single-port 256 × 36	0	1	315	274	238	200	157	MHz
	Simple dual-port 256 × 36 CLK	0	1	315	274	238	200	157	MHz
	True dual port 512 × 18 single CLK	0	1	315	274	238	200	157	MHz

Configuration and JTAG Specifications

Table 1–28 lists the configuration mode specifications for Cyclone IV devices.

Table 1–28. Passive Configuration Mode Specifications for Cyclone IV Devices (1)

Programming Mode	V _{CCINT} Voltage Level (V)	DCLK f _{max}	Unit
Passivo Sorial (PS)	1.0 <i>(3)</i>	66	MHz
rassive Serial (rS)	1.2	133	MHz
East Passivo Parallol (EDD) (2)	1.0 <i>(3)</i>	66	MHz
TASL FASSIVE FAIAIIEI (FFF) (-)	1.2 (4)	100	MHz

Notes to Table 1-28:

- (1) For more information about PS and FPP configuration timing parameters, refer to the *Configuration and Remote System Upgrades in Cyclone IV Devices* chapter.
- (2) FPP configuration mode supports all Cyclone IV E devices (except for E144 package devices) and EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 only.
- (3) V_{CCINT} = 1.0 V is only supported for Cyclone IV E 1.0 V core voltage devices.
- (4) Cyclone IV E devices support 1.2 V V_{CCINT}. Cyclone IV E 1.2 V core voltage devices support 133 MHz DCLK f_{MAX} for EP4CE6, EP4CE10, EP4CE15, EP4CE22, EP4CE30, and EP4CE40 only.

Symbol	Modos		C6			C7, I	7		C8, A	7		C8L, I	BL		C9L		llnit
	Modes	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t _{LOCK} <i>(3)</i>			_	1			1			1		_	1			1	ms

Table 1–31. RSDS Transmitter Timing Specifications for Cyclone IV Devices (1), (2), (4) (Part 2 of 2)

Notes to Table 1-31:

(1) Applicable for true RSDS and emulated RSDS_E_3R transmitter.

(2) Cyclone IV E devices—true RSDS transmitter is only supported at the output pin of Row I/O Banks 1, 2, 5, and 6. Emulated RSDS transmitter is supported at the output pin of all I/O Banks. Cyclone IV GX devices—true RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the

pin of I/O Banks 3, 4, 5, 6, 7, 8, and 9.
(3) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.

(4) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

Cumbol	Madaa	C6				C7, 17			C8, A7			C8L, I8	BL		11!4		
Symbol	wodes	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
	×10	5	—	85	5	—	85	5	—	85	5	—	85	5	—	72.5	MHz
	×8	5	—	85	5	—	85	5	—	85	5	—	85	5	—	72.5	MHz
f _{HSCLK} (input	×7	5	—	85	5	—	85	5	—	85	5	—	85	5	—	72.5	MHz
frequency)	×4	5	—	85	5	—	85	5	—	85	5	—	85	5	—	72.5	MHz
	×2	5	—	85	5	—	85	5	—	85	5	—	85	5	—	72.5	MHz
	×1	5	—	170	5	—	170	5	—	170	5	—	170	5	—	145	MHz
	×10	100	—	170	100	—	170	100	—	170	100	—	170	100	—	145	Mbps
	×8	80	—	170	80	—	170	80	—	170	80	—	170	80	—	145	Mbps
Device	×7	70	—	170	70	—	170	70	—	170	70	—	170	70	—	145	Mbps
Mbps	×4	40	—	170	40	—	170	40	—	170	40	—	170	40	—	145	Mbps
	×2	20	—	170	20	—	170	20	—	170	20	—	170	20	—	145	Mbps
	×1	10	—	170	10	—	170	10	—	170	10	—	170	10	—	145	Mbps
t _{DUTY}	—	45	—	55	45	—	55	45	—	55	45	—	55	45	—	55	%
TCCS	_	—	—	200	—	—	200	—	—	200	—	—	200	—	—	200	ps
Output jitter (peak to peak)	_	_	_	500	_	_	500	_	_	550	_	_	600	_	_	700	ps
	20-80%,																
t _{RISE}	C _{LOAD} = 5 pF	-	500	_	-	500	_	_	500	_	_	500	-	—	500	_	ps
	20-80%,																
t _{FALL}	C _{LOAD} = 5 pF	—	500	-	-	500	-	-	500	-	-	500	-		500	-	ps

 Table 1–32. Emulated RSDS_E_1R Transmitter Timing Specifications for Cyclone IV Devices (1), (3) (Part 1 of 2)

Table 1-46. Glossary (Part 5 of 5)

Letter	Term	Definitions								
	V _{CM(DC)}	DC common mode input voltage.								
	V _{DIF(AC)}	AC differential input voltage: The minimum AC input differential voltage required for switching.								
	V _{DIF(DC)}	DC differential input voltage: The minimum DC input differential voltage required for switching.								
	V _{ICM}	Input common mode voltage: The common mode of the differential signal at the receiver.								
	V _{ID} Input differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.									
	V _{IH}	Voltage input high: The minimum positive voltage applied to the input that is accepted by the device as a logic high.								
	V _{IH(AC)}	High-level AC input voltage.								
	V _{IH(DC)}	High-level DC input voltage.								
	V _{IL}	Voltage input low: The maximum positive voltage applied to the input that is accepted by the device as a logic low.								
	V _{IL (AC)}	Low-level AC input voltage.								
	V _{IL (DC)}	Low-level DC input voltage.								
	V _{IN}	DC input voltage.								
	V _{OCM}	Output common mode voltage: The common mode of the differential signal at the transmitter.								
v	V _{OD}	Output differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter. $V_{OD} = V_{OH} - V_{OH}$								
	V _{OH} Voltage output high: The maximum positive voltage from an output that the device accepted as the minimum positive high level.									
	V _{OL}	Voltage output low: The maximum positive voltage from an output that the device considers is accepted as the maximum positive low level.								
	V _{OS}	Output offset voltage: $V_{OS} = (V_{OH} + V_{OL}) / 2$.								
	V _{OX (AC)}	AC differential output cross point voltage: the voltage at which the differential output signals must cross.								
	V _{REF}	Reference voltage for the SSTL and HSTL I/O standards.								
	V _{REF (AC)}	AC input reference voltage for the SSTL and HSTL I/O standards. $V_{REF(AC)} = V_{REF(DC)} + noise$. The peak-to-peak AC noise on V_{REF} must not exceed 2% of $V_{REF(DC)}$.								
	V _{REF (DC)}	DC input reference voltage for the SSTL and HSTL I/O standards.								
	V _{SWING (AC)}	AC differential input voltage: AC input differential voltage required for switching. For the SSTL differential I/O standard, refer to Input Waveforms.								
	V _{SWING (DC)}	DC differential input voltage: DC input differential voltage required for switching. For the SSTL differential I/O standard, refer to Input Waveforms.								
	V _{TT}	Termination voltage for the SSTL and HSTL I/O standards.								
	V _{X (AC)}	AC differential input cross point voltage: The voltage at which the differential input signals must cross.								
W	_	—								
X	—	—								
Y	—	—								
Z		—								